

## Reliability Test Summary

No	Test Item	Test Condition	Test Foundation	Quality Level
1	Solderability	Dip in flux Time=5sec. Temp.of solder Pot=245±5°C , Time= 5~10 sec.	MIL-STD-750D Method 2026	Ac/Rj=22/0
2	Soldering Heat	Temp of solder pot=260±5°C , Time= 10~12 sec	MIL-STD-750D Method 2031	Ac/Rj=22/0
3	Temperature Cycle	Tstg(min.)to tstg(max.) dwelled for 30 min and transfer time not exceed 1 min; 20 cycles	MIL-STD-750D Method 1051	Ac/Rj=22/0
4	Thermal Shock Test	Ta1 = 100 °C Time = 10 min then ta2= 0 °C , Tim= 10 min for 20 cycles,transfer time must not exseed 5sec.	MIL-STD-750D Method 1056	Ac/Rj=22/0
5	Steady State Operation Life Test	I=Io Time=1000hrs.	MIL-STD-750D Method 1027	Ac/Rj=22/0
6	High Temperature Reverse Bias Life	VR= 80% VR Ta= TJ MAX. (depend on product) Test Time 1000 hrs.	MIL-STD-750D Method 1038	Ac/Rj=22/0
7	Intermittent Forward Operation Life	If=Io ON 1.5hrs OFF 0.5hrs Test Time : 500Cycles	MIL-STD-750D Method 1036	Ac/Rj=22/0
8	Pressure Cooker Test	Ta= 121°C Pressure= 15 Psi Time= 4 hrs	JESD 22-A102	Ac/Rj=22/0
9	Boiling	100°C Water Time= 5 hrs	-----	Ac/Rj=22/0
10	High Temperature Storage Life	Ta= TSTG MAX. Time= 1000 hrs	MIL-STD-750D Method 1031	Ac/Rj=22/0
11	Humidity	Ta= 85 °C RH= 85% Time=1000 hrs	EIAJ ED-4701	Ac/Rj=22/0